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Aehr Test Systems to Exhibit at Burn-in and Test Strategies Workshop in Mesa, AZ March 6-9

Fremont, CA (March 7, 2016) – Aehr Test Systems (NASDAQ: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced that it will exhibit in Booth A28 at the 17th annual Burn-in and Test Strategies (BiTS) Workshop taking place March 6-9, 2016 in Mesa, Arizona.

The BiTS Workshop is the world's premier workshop dedicated to providing a forum for the latest information about burn-in and test tooling and related fields. It includes a comprehensive technical program, exhibits of the latest products and services, and opportunities to meet, network and explore ideas with other test and burn-in strategies professionals. Additional details on the conference can be found on the BiTS website, www.bitsworkshop.org.

In concert with the theme of the conference, Aehr Test is showcasing its solutions for burn-in and test systems to enhance the reliability of devices produced by semiconductor manufacturers. These solutions include:

- The ABTS™ family of packaged part burn-in and test systems, which are based on a new hardware and software platform that is designed to address not only today's devices, but also future devices for many years to come. This system can test and burn-in high pin-count devices and there are also configurations for high-power and low-power applications.

- The FOX family of products, which includes multi-wafer test solutions that are capable of functional test and burn-in/cycling of flash memories, microcontrollers and other leading edge ICs in wafer form before they are assembled into multi-die stacked packages. The FOX systems utilize Aehr Test's FOX WaferPak contactor, which provides a cost effective solution for making electrical contact with a full wafer or substrate in a multi-wafer environment.

- The FOX-1P system, Aehr Test's second generation of the single-wafer FOX-1 platform originally introduced in 2006, which has proven to be a cost saving high-volume production solution for single touchdown 300mm full-wafer parallel test. The new FOX-1P system can be configured with over 16,000 "Universal Channels" and features a massively parallel test interface which enables testing over a thousand die in a single touchdown.

- The FOX-XP system, the company's next-generation multi-wafer test solution that is capable of functional test and burn-in/cycling of flash memories, microcontrollers, sensors, and other leading-edge ICs in wafer form before they are assembled into single or multi-die stacked

packages. These singulated known-good die or single-die or stacked-die packaged parts can then be used for high reliability and quality applications such as enterprise solid state drives, automotive devices, highly valuable mobile applications, and mission critical integrated circuits and sensors.

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, capacity needs and opportunities for Aehr Test products in package and wafer level test. Aehr Test has developed and introduced several innovative products, including the ABTS^{TM} and FOX families of test and burn-in systems and the DiePak$^®$ carrier. The ABTS system is used in production and qualification testing of packaged parts for both lower-power and higher-power logic as well as all common types of memory devices. The FOX system is a full wafer contact test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit the Company's website at www.aehr.com.

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